## 2-Bit Bus Switch

The 7WB3306 is an advanced high-speed low-power 2-bit bus switch in ultra-small footprints.

#### **Features**

- High Speed:  $t_{PD} = 0.25 \text{ ns (Max)} @ V_{CC} = 4.5 \text{ V}$
- 3 Ω Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Zero Bounce
- TTL-Compatible Control Inputs
- Ultra-Small Pb-Free Packages
- These are Pb-Free Devices



## ON Semiconductor®

http://onsemi.com

#### MARKING DIAGRAMS



UDFN8 MU SUFFIX CASE 517AJ





Micro8™ DM SUFFIX CASE 846A





TSSOP8 DT SUFFIX CASE 948AL





UDFN8 1.95 x 1.0 CASE 517CA



A = Assembly Location

Y = Year
W = Work Week
M = Date Code
= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

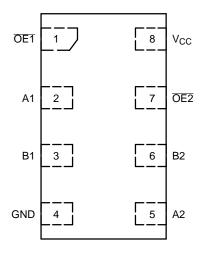


Figure 1. UDFN8 (Top Thru–View)

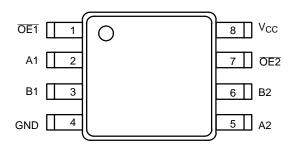


Figure 2. Micro8/TSSOP8 (Top View)

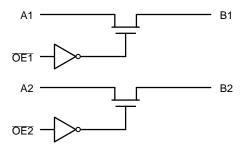


Figure 3. Logic Diagram

## **FUNCTION TABLE**

Input OEn	Function		
L	Bn = An		
Н	Disconnect		

#### **MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Control Pin Input Voltage	-0.5 to +7.0	V	
V <sub>I/O</sub>	Switch Input / Output Voltage		-0.5 to +7.0	V
I <sub>IK</sub>	Control Pin DC Input Diode Current	V <sub>IN</sub> < GND	-50	mA
I <sub>OK</sub>	Switch I/O Port DC Diode Current	V <sub>I/O</sub> < GND	-50	mA
IO	ON-State Switch Current		± 128	mA
	Continuous Current Through V <sub>CC</sub> or GND		± 150	mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin		± 150	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		± 150	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Sec	onds	260	°C
TJ	Junction Temperature Under Bias		150	°C
$\theta_{\sf JA}$	Thermal Resistance	UDFN8 (Note 1) Micro8 TSSOP8	111 392 150	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	UDFN8 Micro8 TSSOP8	1127 319 833	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34		UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2) Human Body Model, all pins Human Body Model, $A_n/B_n$ to Ground Human Body Model, $A_n/B_n$ to $V_{CC}$		> 1.5 > 4 > 4	kV kV kV
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below G	ND at 125°C (Note 3)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
- Tested to EIA / JESD22-A114-A.
   Tested to EIA / JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Positive DC Supply Voltage	4.0	5.5	V	
V <sub>IN</sub>	Control Pin Input Voltage	0	5.5	V	
V <sub>I/O</sub>	Switch Input / Output Voltage	0	5.5	V	
T <sub>A</sub>	Operating Free–Air Temperature	<b>-</b> 55	+125	°C	
Δt/ΔV	Input Transition Rise or Fall Rate	Control Input Switch I/O	0	5 DC	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

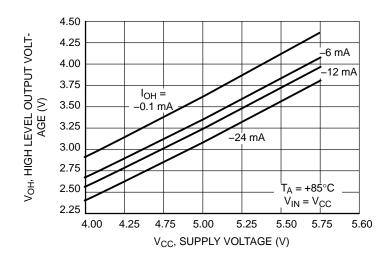
			V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C to +125°C		
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IK</sub>	Clamp Diode Voltage	$I_{I/O} = -18 \text{ mA}$	4.5			-1.2		-1.2	V
V <sub>IH</sub>	High-Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
$V_{IL}$	Low-Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
V <sub>OH</sub>	Output Voltage High	See Figure 4							
I <sub>IN</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±0.1		±1.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	$V_{I/O} = 0 \text{ to } 5.5 \text{ V}$	0			±0.1		±1.0	μΑ
Icc	Quiescent Supply Current	$I_O = 0$ , $V_{IN} = V_{CC}$ or 0 V	5.5			± 0.1		±1.0	μΑ
$\Delta I_{CC}$	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V <sub>CC</sub> or GND	5.5					2.5	mA
R <sub>ON</sub>	Switch ON Resistance	$V_{I/O} = 0,$ $I_{I/O} = 64 \text{ mA}$ $I_{I/O} = 30 \text{ mA}$	4.5		3 3	7 7		7 7	Ω
		$V_{I/O} = 2.4,$ $I_{I/O} = 15 \text{ mA}$			6	15		15	
		$V_{I/O} = 2.4,$ $I_{I/O} = 15 \text{ mA}$	4.0		10	20		20	

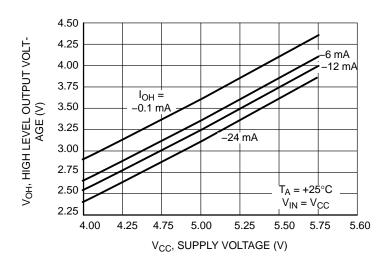
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **AC ELECTRICAL CHARACTERISTICS**

			V <sub>CC</sub>	1	T <sub>A</sub> = 25 °C		T <sub>A</sub> = -55°C to +125°C		
Symbol	Parameter	Test Condition	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PD</sub>	Propagation Delay, Bus to Bus	See Figure 5	4.0 to 5.5			0.25		0.25	ns
t <sub>EN</sub>	Output Enable Time	See Figure 5	4.5 to 5.5	0.8	2.5	4.2	0.8	4.2	ns
			4.0	0.8	3.0	4.6	0.8	4.6	
t <sub>DIS</sub>	Output Disable Time		4.5 to 5.5	0.8	3.0	4.8	0.8	4.8	ns
			4.0	0.8	2.9	4.4	0.8	4.4	
C <sub>IN</sub>	Control Input Capacitance	V <sub>IN</sub> = 5 or 0 V	5.0		2.5				pF
C <sub>IO(ON)</sub>	Switch On Capacitance	Switch ON	5.0		10				pF
C <sub>IO(OFF)</sub>	Switch Off Capacitance	Switch OFF	5.0		5				pF

## **TYPICAL DC CHARACTERISTICS**





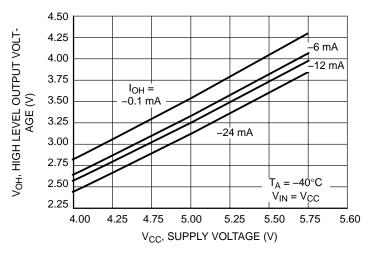
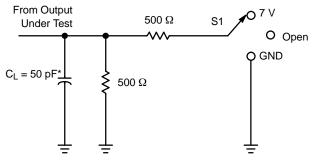


Figure 4. Output Voltage High vs Supply Voltage

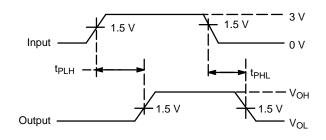
#### **AC LOADING AND WAVEFORMS**

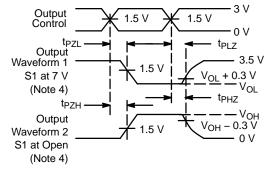
#### **Parameter Measurement Information**



Test	<b>S</b> 1
t <sub>PD</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	7 V
t <sub>PHZ</sub> /t <sub>PZH</sub>	Open

<sup>\*</sup>C<sub>L</sub> includes probes and jig capacitance.





### **Voltage Waveforms Propagation Delay Times**

**Voltage Waveforms Enable and Disable Times** 

- 4. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
- 5. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_r \leq$  2.5 ns,  $t_f \leq$  2.5 ns. 6. The outputs are measured one at a time, with one transition per measurement.
- t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>DIS</sub>.
- t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>EN</sub>.
   t<sub>PHL</sub> and t<sub>PLH</sub> are the same as t<sub>PD</sub>.

Figure 5. t<sub>PD</sub>, t<sub>EN</sub>, t<sub>DIS</sub> Loading and Waveforms

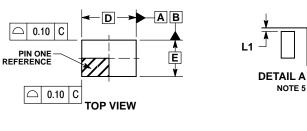
## **ORDERING INFORMATION**

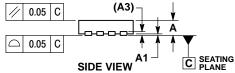
Device	Package	Shipping <sup>†</sup>	
7WB3306MUTAG	UDFN8 (Pb-Free)	3000 / Tape & Reel	
7WB3306DMR2G	Micro8 (Pb-Free)	4000 / Tape & Reel (In Developmant)	
7WB3306DTR2G TSSOP8 (Pb-Free)		5000 / Tape & Reel	
7WB3306DMUTCG	UDFN8, 1.95 x 1.0, 0.5 mm Pitch (Pb-Free)	3000 / Tape & Reel	

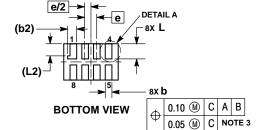
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

#### **UDFN8 1.8 x 1.2, 0.4P** CASE 517AJ **ISSUE O**



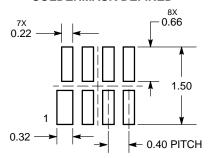




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
  4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
  5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

	<b>MILLIMETERS</b>				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
A3	0.127	REF			
b	0.15	0.25			
b2	0.30	REF			
D	1.80	BSC			
Е	1.20	BSC			
е	0.40	BSC			
L	0.45 0.55				
L1	0.00	0.03			
L2	0.40	REF			

#### **MOUNTING FOOTPRINT\* SOLDERMASK DEFINED**

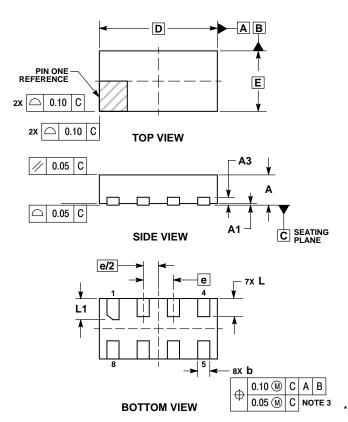


DIMENSIONS: MILLIMETERS

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **PACKAGE DIMENSIONS**

UDFN8 1.95x1.0, 0.5P CASE 517CA ISSUE O



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

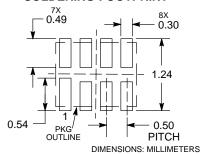
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.

  4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS					
DIM	MIN MAX					
Α	0.45	0.55				
A1	0.00	0.05				
А3	0.13 REF					
b	0.15	0.25				
D	1.95	BSC				
Е	1.00	BSC				
е	0.50 BSC					
L	0.25	0.35				
L1	0.30	0.40				

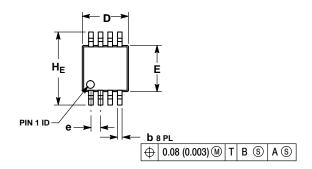
#### **RECOMMENDED SOLDERING FOOTPRINT\***

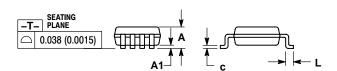


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **PACKAGE DIMENSIONS**

Micro8™ CASE 846A **ISSUE H** 





#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

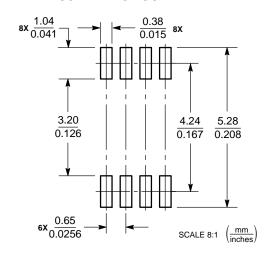
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.06) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10		1	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
С	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
Е	2.90	3.00	3.10	0.114	0.118	0.122
е		0.65 BSC		0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
HE	4.75	4.90	5.05	0.187	0.193	0.199

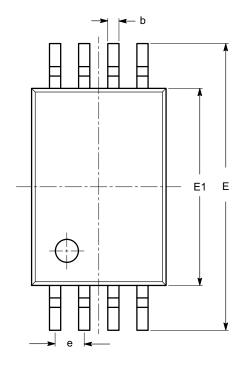
## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

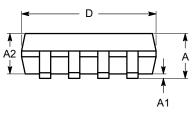
#### PACKAGE DIMENSIONS

TSSOP8, 4.4x3 CASE 948AL **ISSUE O** 

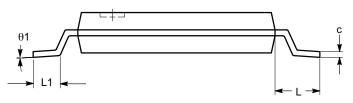


SYMBOL	MIN	NOM	MAX	
Α			1.20	
A1	0.05		0.15	
A2	0.80	0.90	1.05	
b	0.19		0.30	
С	0.09		0.20	
D	2.90	3.00	3.10	
Е	6.30	6.40	6.50	
E1	4.30	4.40	4.50	
е		0.65 BSC		
L	1.00 REF			
L1	0.50	0.60	0.75	
θ	0°		8°	





SIDE VIEW



#### **END VIEW**

#### Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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